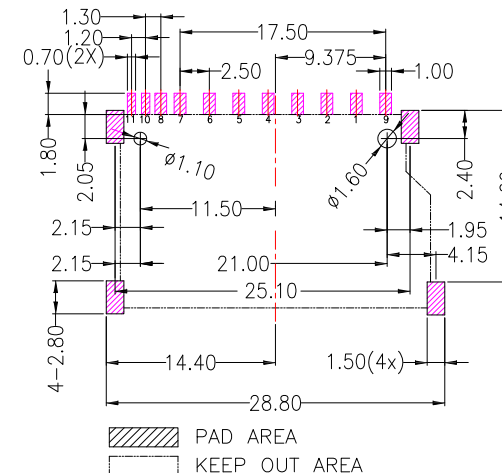
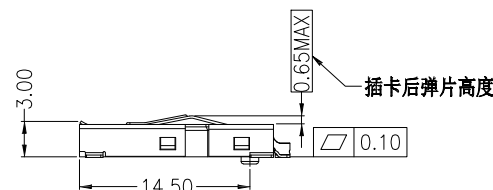
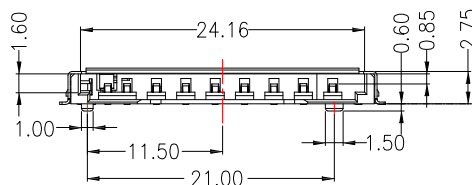
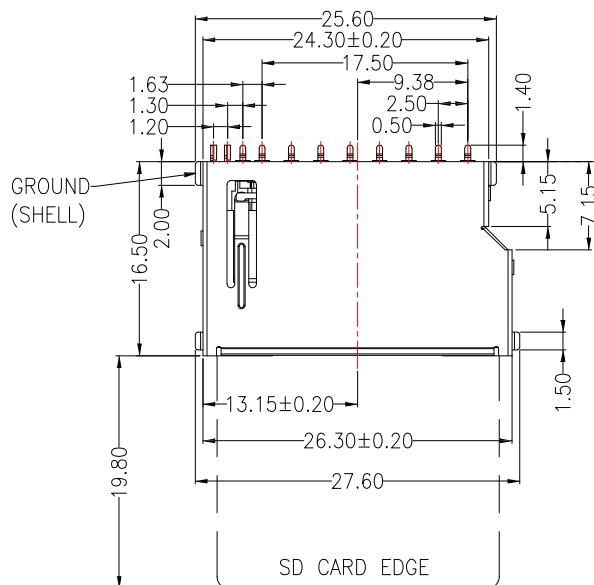


SD CARD PIN DESIGN

PIN NO.	NAME	DESCRIPTION
1#	CD/DAT3	CARD DETECT/DATA I/O
2#	CMD	COMMAND
3#	VSS1	GROUND
4#	VDD	POWER
5#	CLK	CLOCK
6#	VSS2	GROUND
7#	DAT0	DATA I/O
8#	DAT1	DATA I/O
9#	DAT2	DATA I/O
10#	CD	
11#	WP	



P.C.B LAYOUT

1.MATERIAL:

1.1 HOUSING: LCP

1.2 CONTACT: PHOSPHOR BRONZE

1.3 COVER: BRASS

2.PLATING:

2.1 CONTACT: PLATED GOLD IN MATING AREA ;

TIN PLATED ON SOLDER BALLS ;

NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.ELECTRICAL & MECHANICAL PARAMETER

3.1 CURRENT RATING: 0.5A

3.2 CONTACT RESISTANCE: 100mΩ MAX

3.3 INSULATION RESISTANCE: 1000MΩ MIN

3.4 WITHSTANDING STRENGTH: 500V AC

3.5 INSERTION FORCE: 10N MAX

3.6 SEPARATION FORCE: 2N MIN

3.7 OPERATING TEMPERATURE: -25℃ ~ 90℃

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
DATE: 04/09/26

CHECKED BY: Jacky Chen
DATE: 04/09/26

APPROVED BY: Tony Kao
DATE: 04/09/26

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	SD 短體卡座 H3.0mm
SCALE	DWG NO.	SD-T125012-S502
SHEET NO.	PART NO.	SD-T125012-S502

ITEM NO.	DESCRIPTION	DRAWN	DATE
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